

III-V epitaxy for low energy optoelectronics

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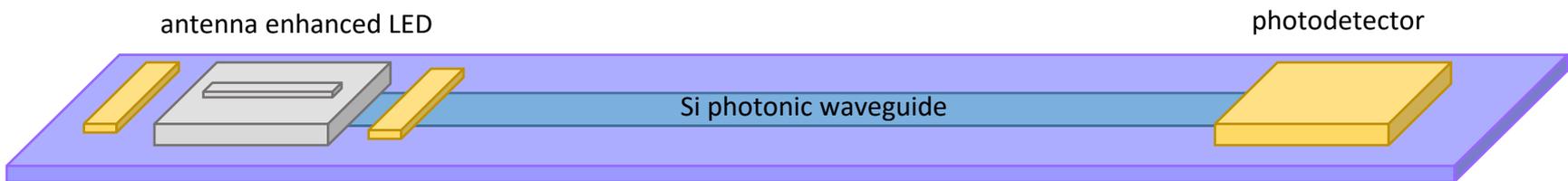
**III-V: Yunjo Kim, Kuangye Lu
III-N: Kuan Qiao, Yunpeng Liu
Oxide: Sangho Lee**

Postdoc

**Sanghoon Bae, Hyunseok Kim
Wei Kong
Hyun Kum**

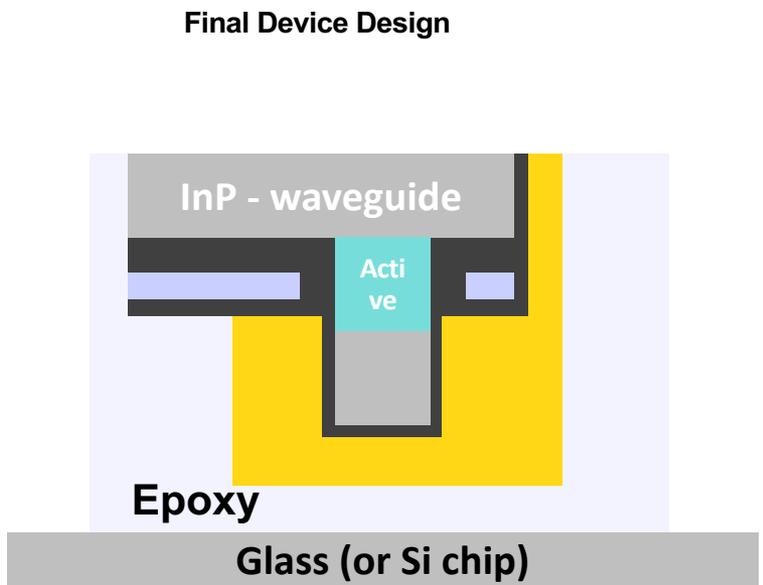
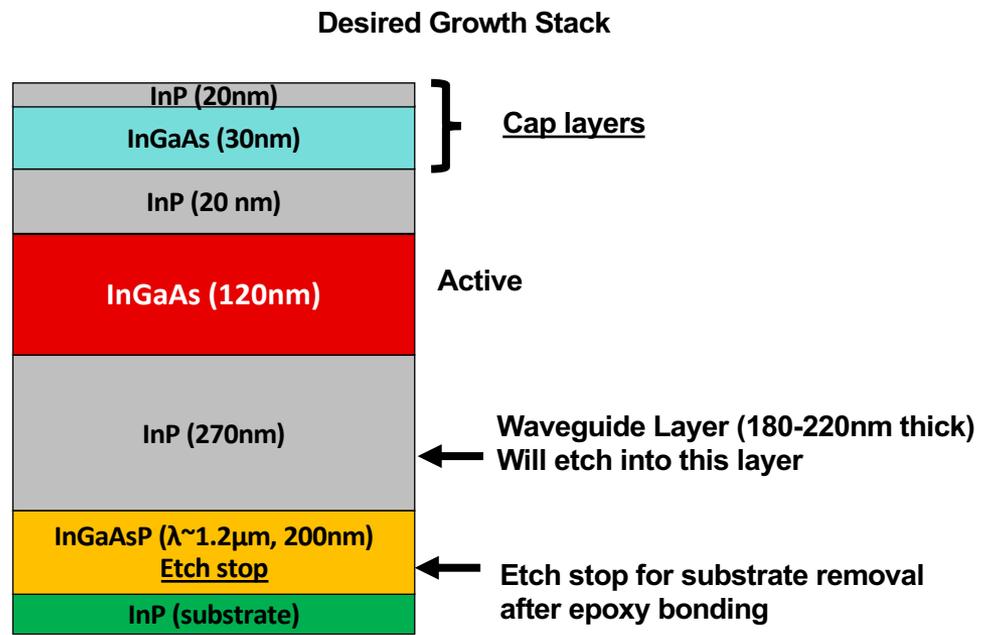


Epitaxial strategies enabling low energy optoelectronics



Thrust 1: Optimization of LED stack

Thrust 2: Layer transfer technology for heterointegration



Etch stop optimization

Calibration of InGaAsP ($\lambda = 1200\text{nm}$) etch stop

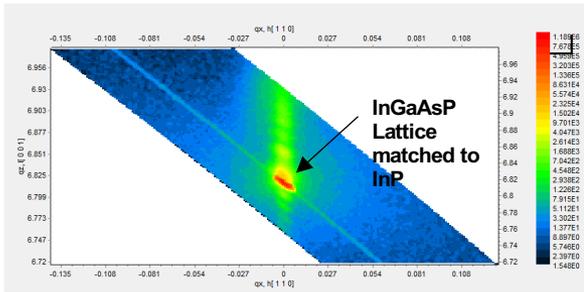
Assuming distribution coefficient remain constant with incremented flowrates

Flow rates were adjusted accordingly to achieve target composition of $\text{In}_{0.729}\text{Ga}_{0.271}\text{As}_{0.585}\text{P}_{0.415}$

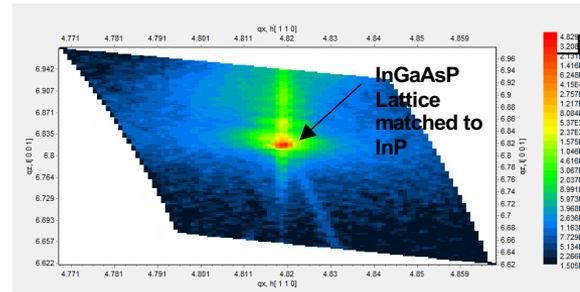
TMIn (mol/min)	TMGa (mol/min)	PH3 (mol/min)	AsH3 (mol/min)
6.56E-5	1.758E-5	1.35E-2	5.960E-4

XRD RSM analysis

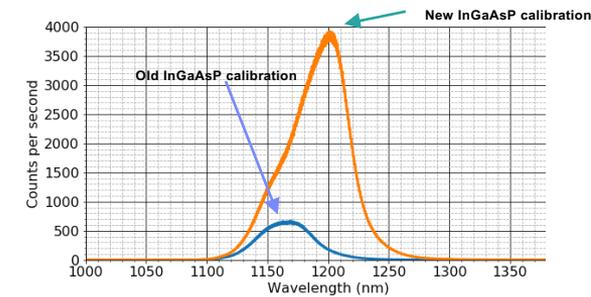
[004] reciprocal lattice index



[224] reciprocal lattice index



PL Spectra

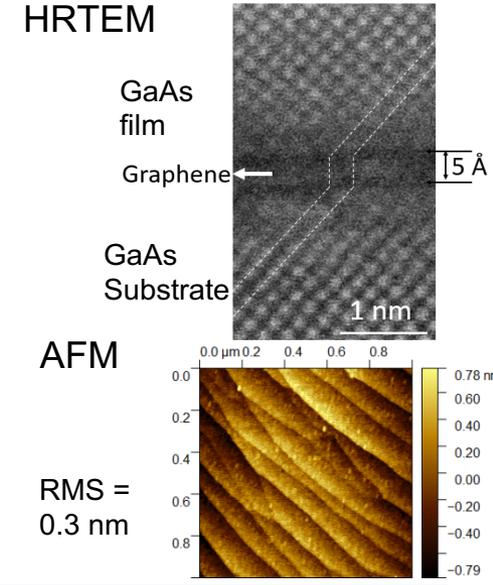
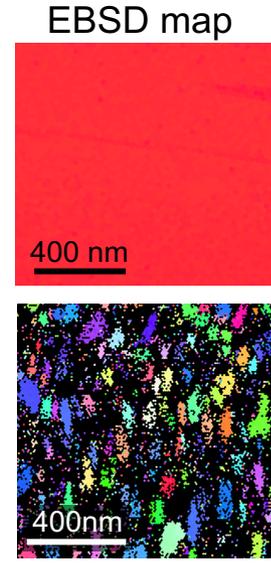
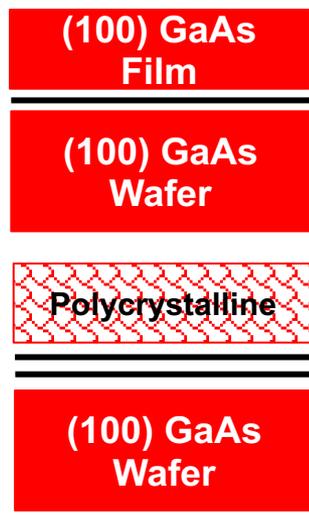
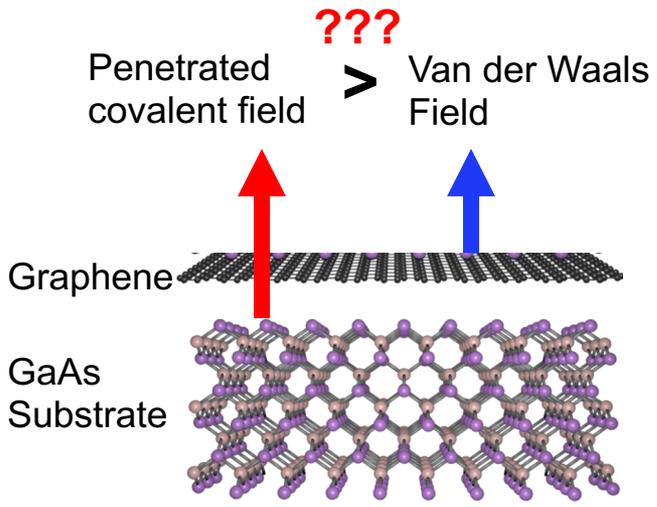


new $\lambda_{\text{peak}} = 1202 \text{ nm}$

Negligible shift in the distribution coefficient was observed, target composition was achieved in updated recipe

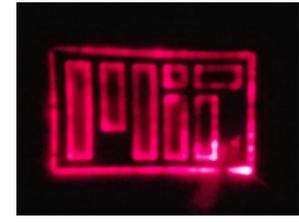
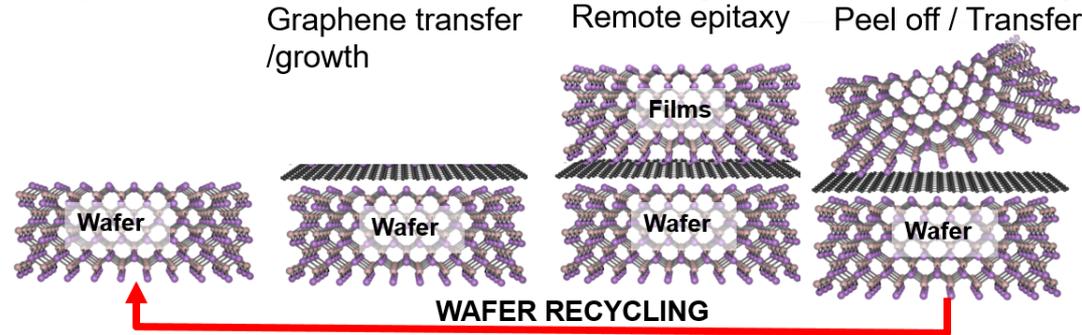
Increase in PL peak intensity was attributed lower contamination in InGaAsP layer due to prior effort to decontaminate chamber before growth

Strategy to interintegrate nano-LED on Si: Remote epitaxy

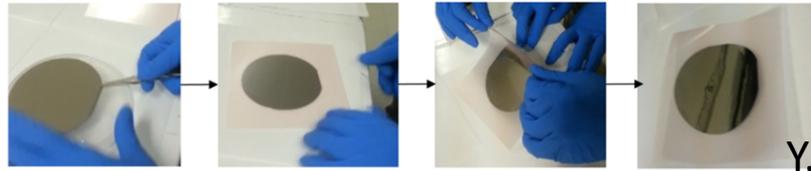


Perfect single-crystalline planar films can be grown on 2D materials

Application: 2D material-based layer transfer (2DLT)



Monolayer graphene + Wafer = Copy Machine (Film producer)

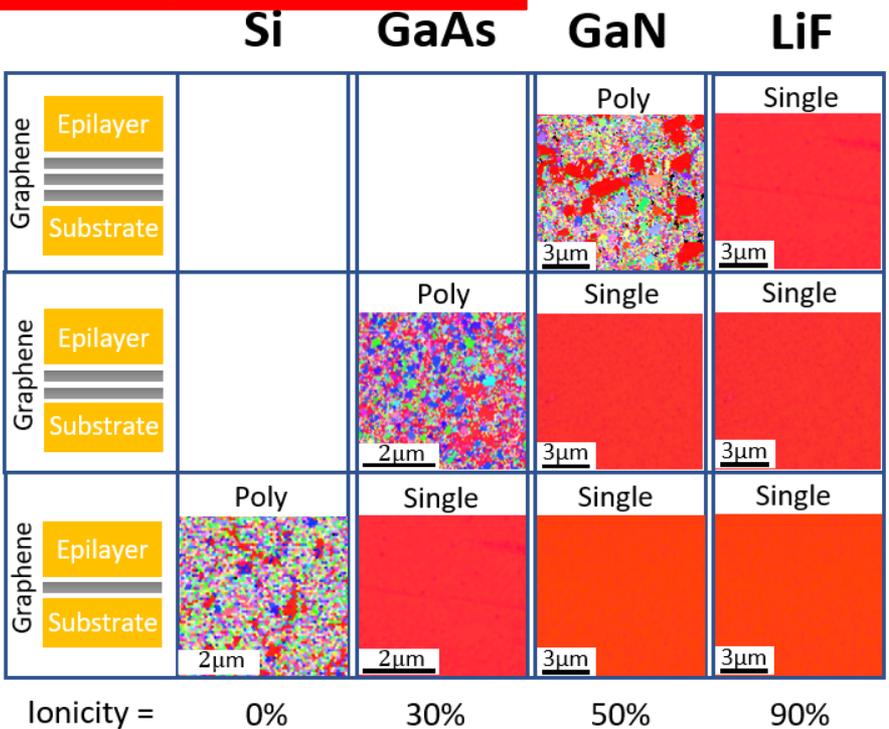


Y. Kim et al., and J. Kim., **Nature** 544, 340 (2017)

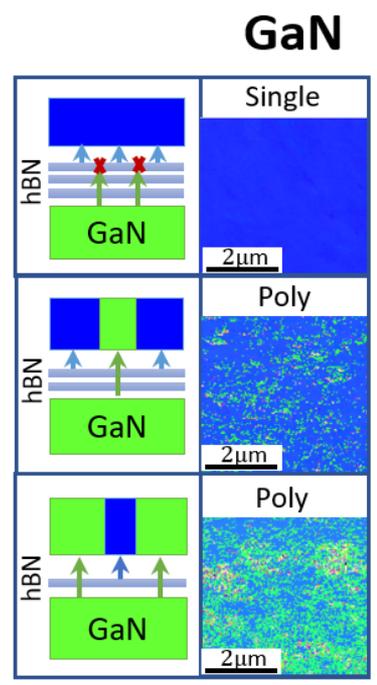
Polarity governs remote atomic interaction through 2D materials

DFT thermodynamic calculation

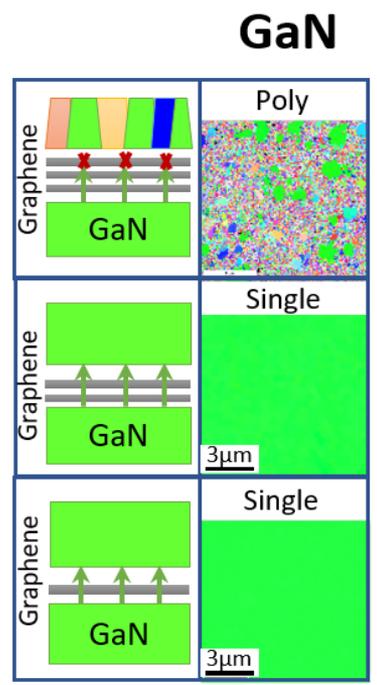
Non-polar 2D interlayer



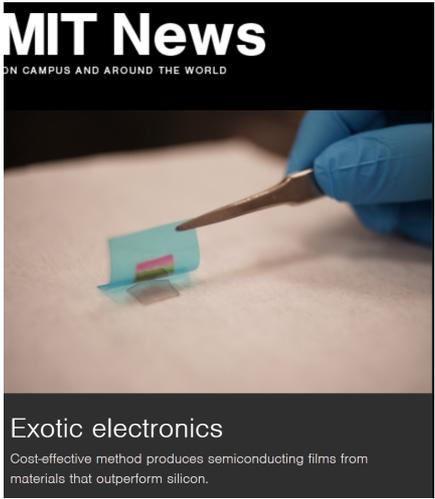
hBN interlayer (Polar)



Graphene interlayer (Non-Polar)



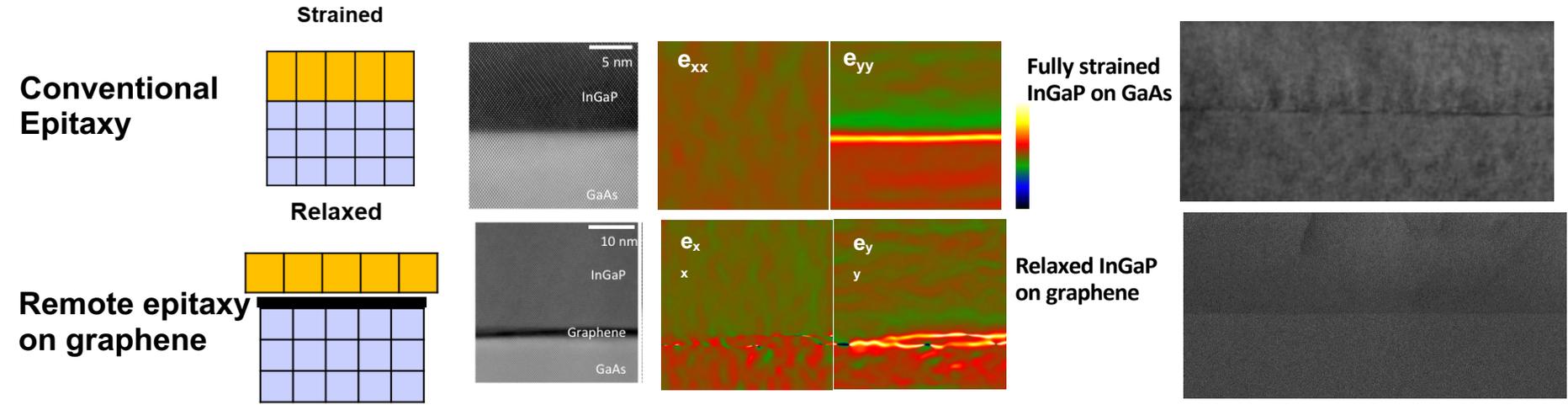
Polarity of 3D materials determines field penetration
 Polarity of 2D materials determines field screening



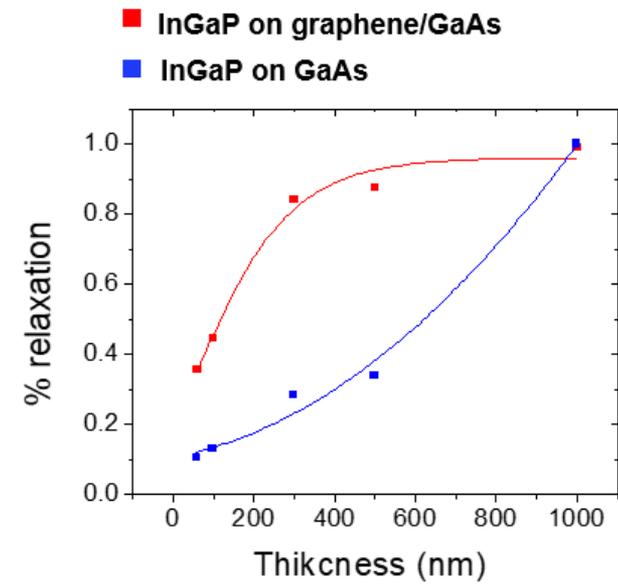
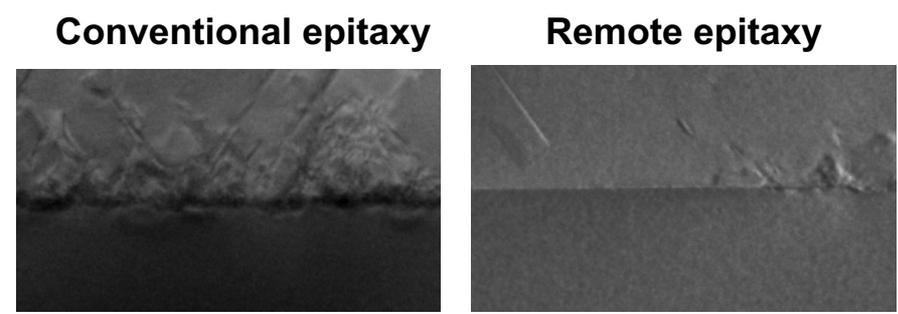
W. Kong,...and J. Kim*, *Nature Materials*, Vol. 17, 335 (2018)
 S. Bae..., and J. Kim*, *Nature Materials*, Vol 18, 550 (2019)

Remote heteroepitaxy: Dislocation-free heteroepitaxy

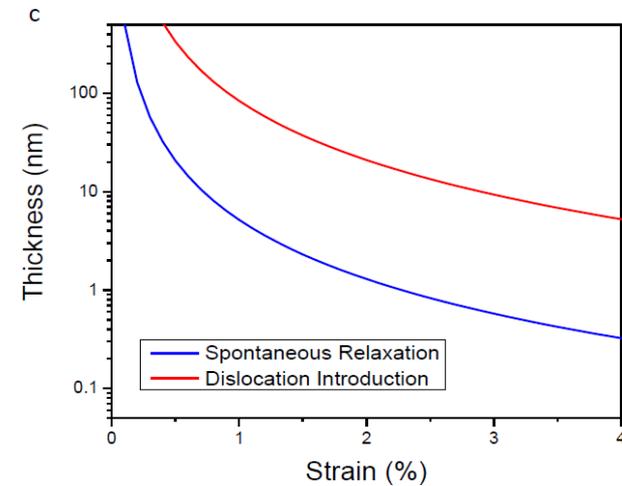
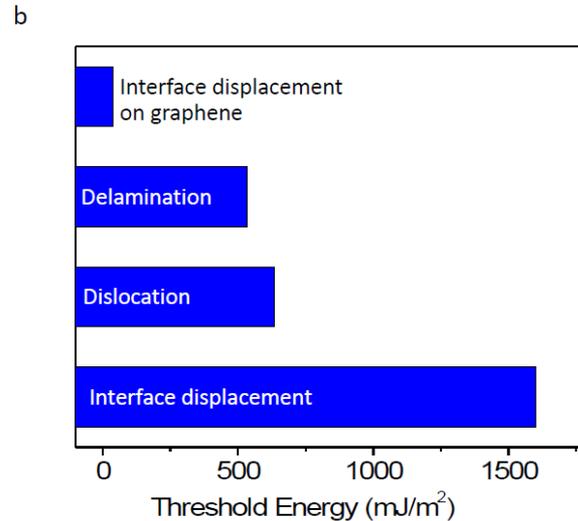
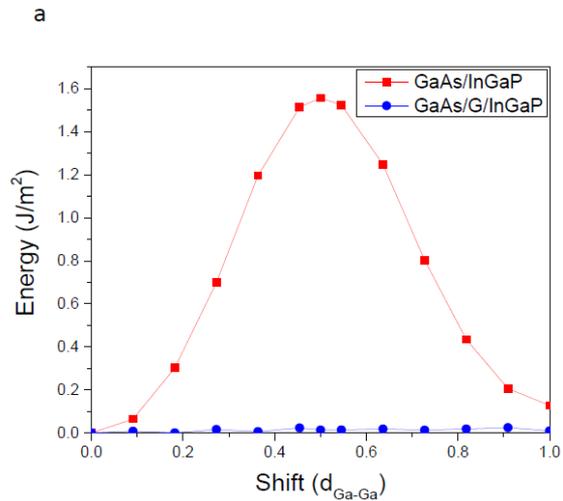
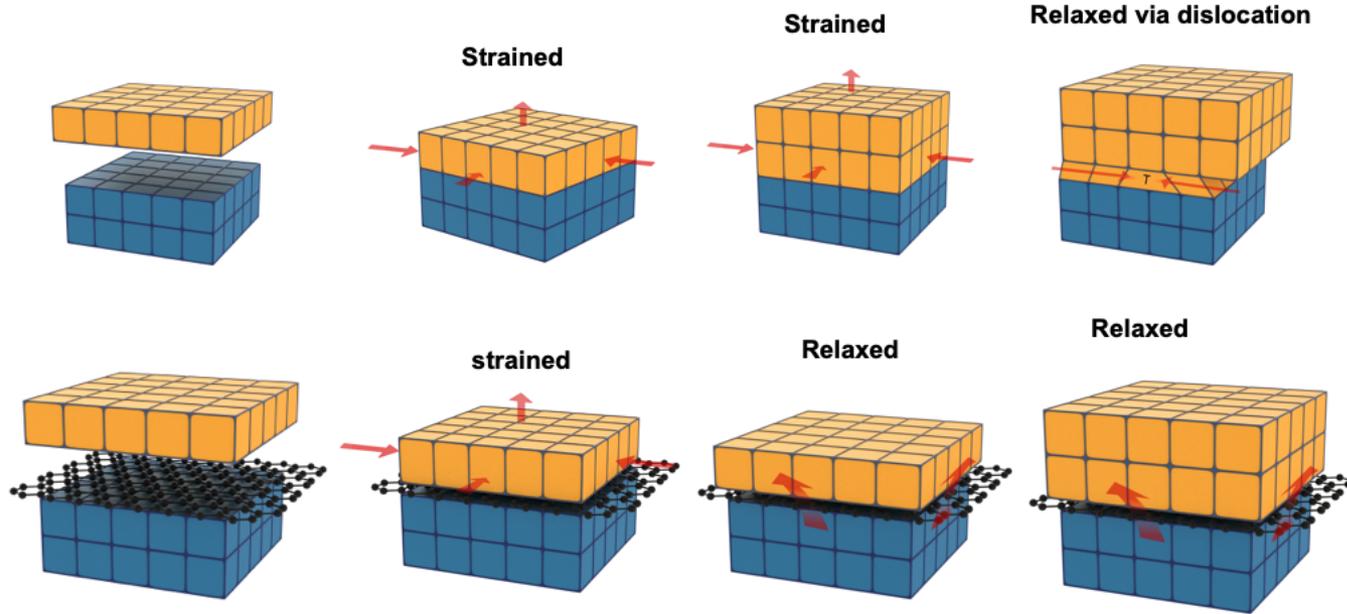
1% strained InGaP on GaAs



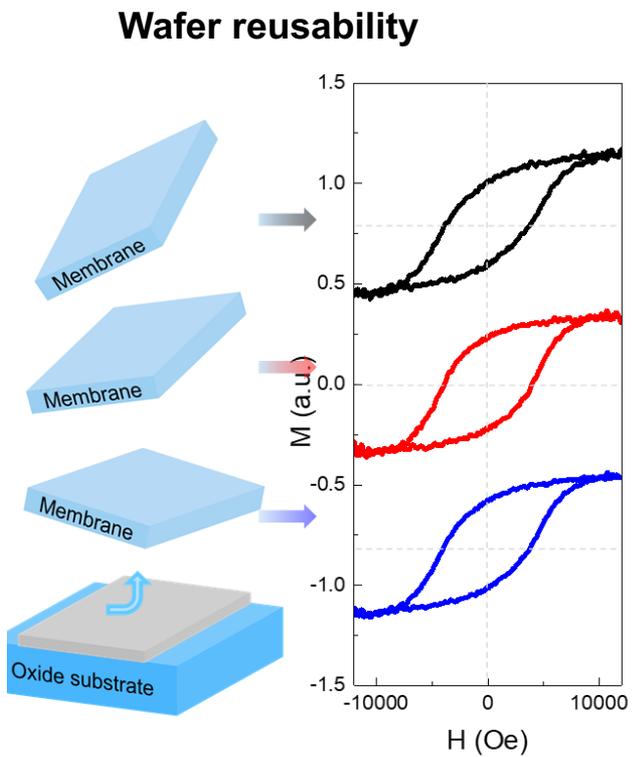
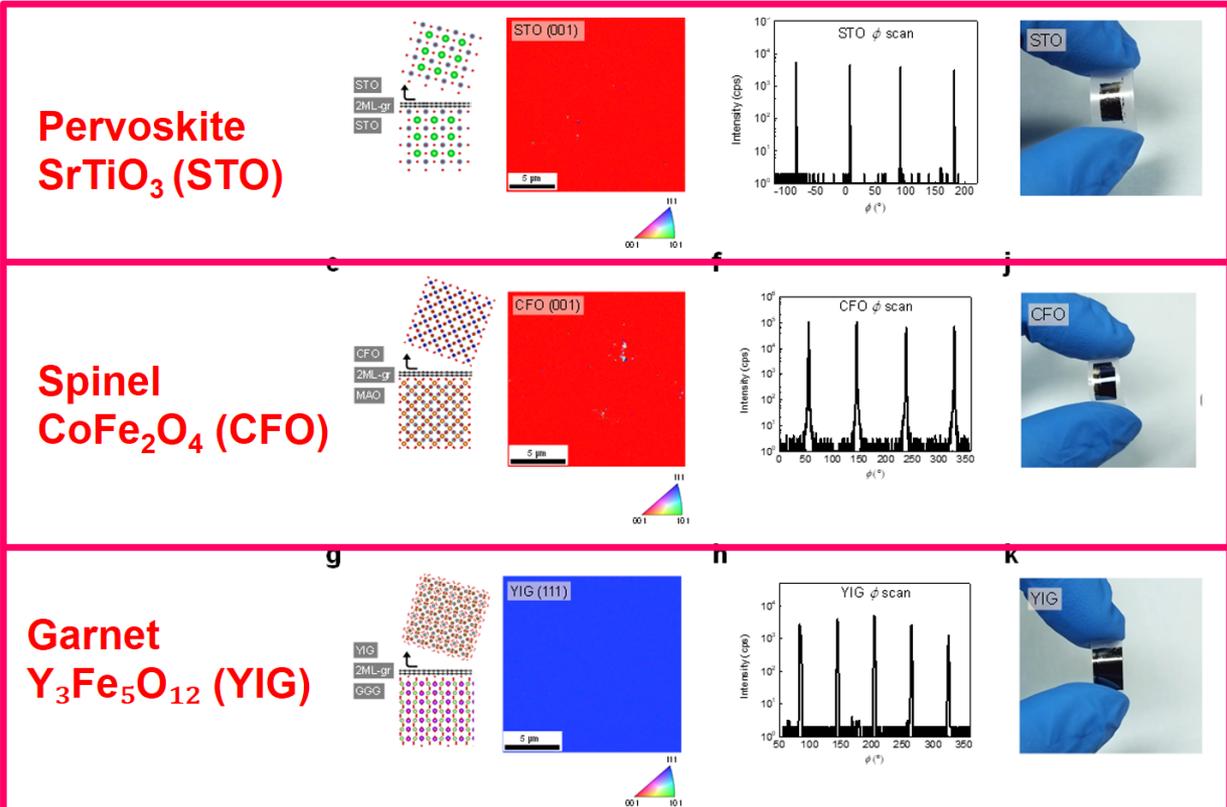
4% strained GaP on GaAs



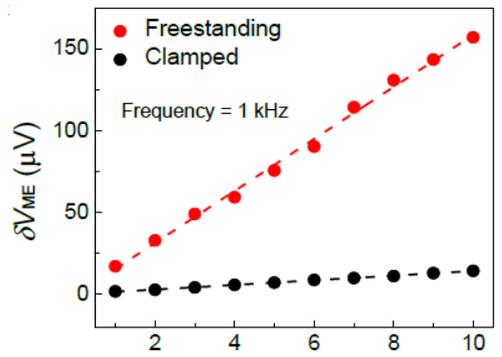
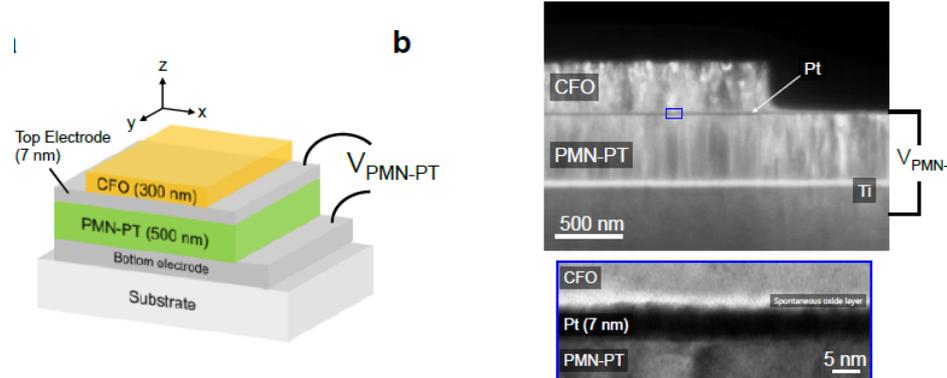
New critical thickness on slippery graphene



Remote epitaxy for complex oxides

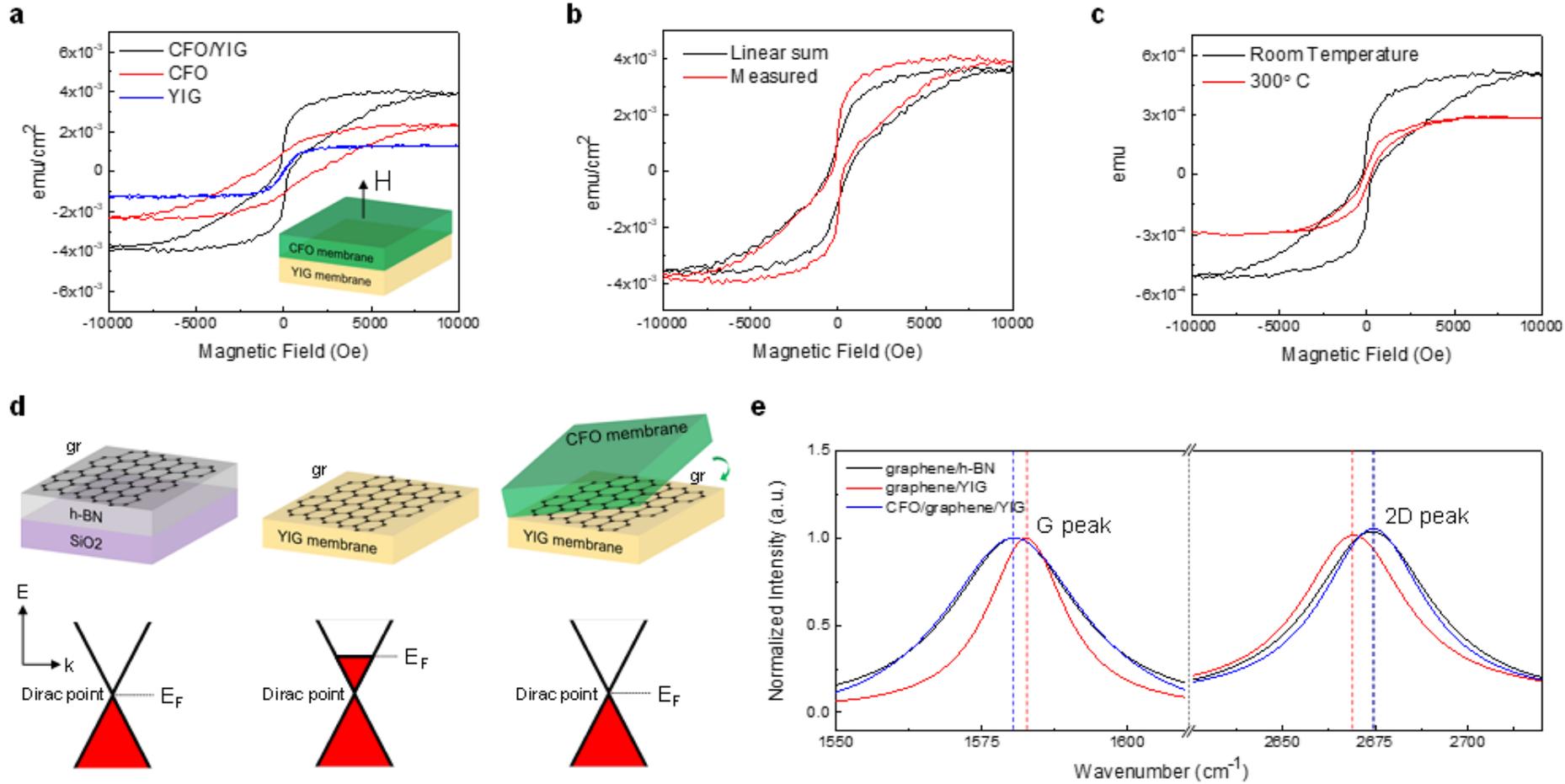


Heterointegration: Magnetoelectric coupling of freestanding oxides (PMNPT+CFO)



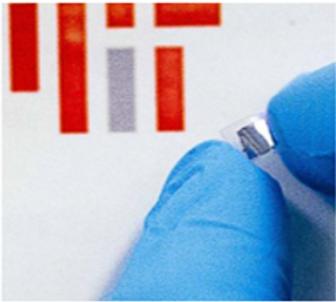
Heterointegration of complex oxides

Magnetostatic + electrical coupling of freestanding oxides (YIG + CFO)

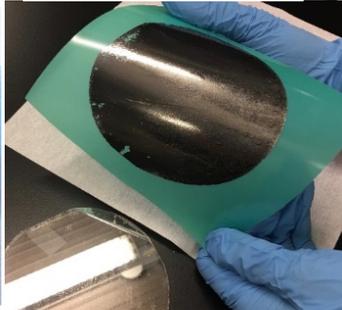


Potential of remote epitaxy

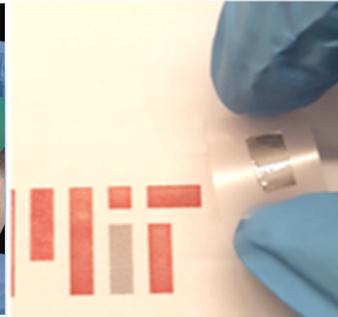
GaAs (III-V)



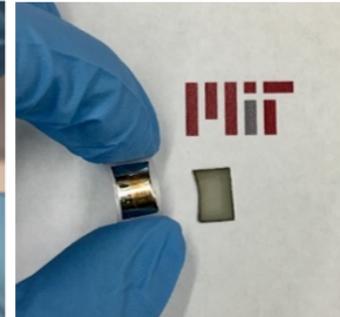
GaN (III-N)



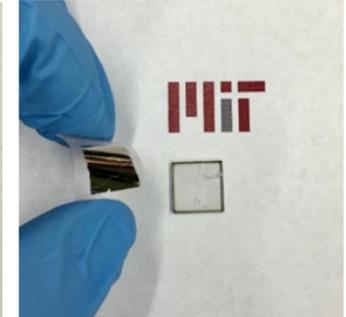
InP (III-V)



SrTiO₃ (Oxide)



LiF (fluoride)



MicroLEDs

High efficiency PV
Transistor

Wireless system
Power system

Photodetector

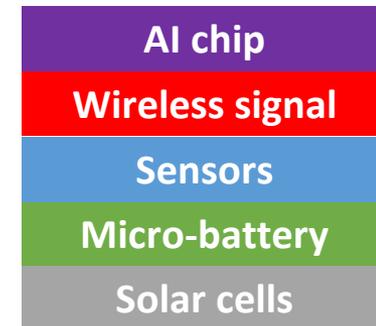
Piezoelectric sensor

Optical waveguide
Battery

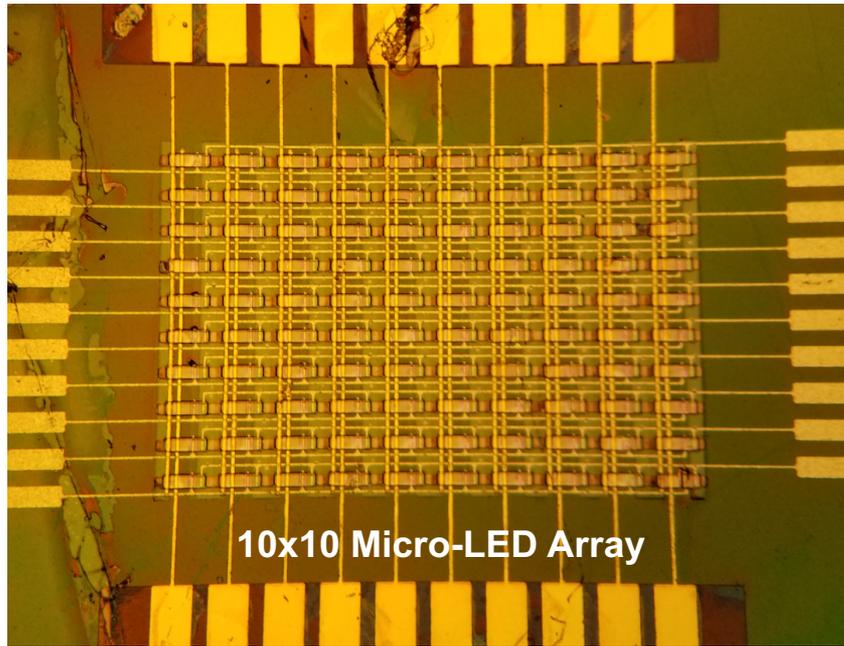


Monolayer graphene + Wafer
= Copy Machine (Film producer)

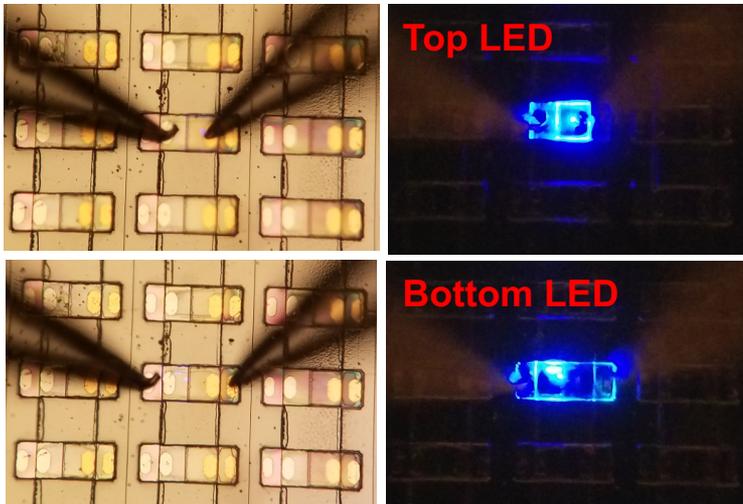
Self-powered/analyzed
electronic wireless system



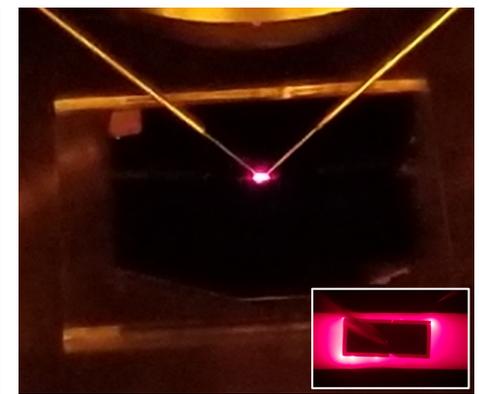
↑
sunlight



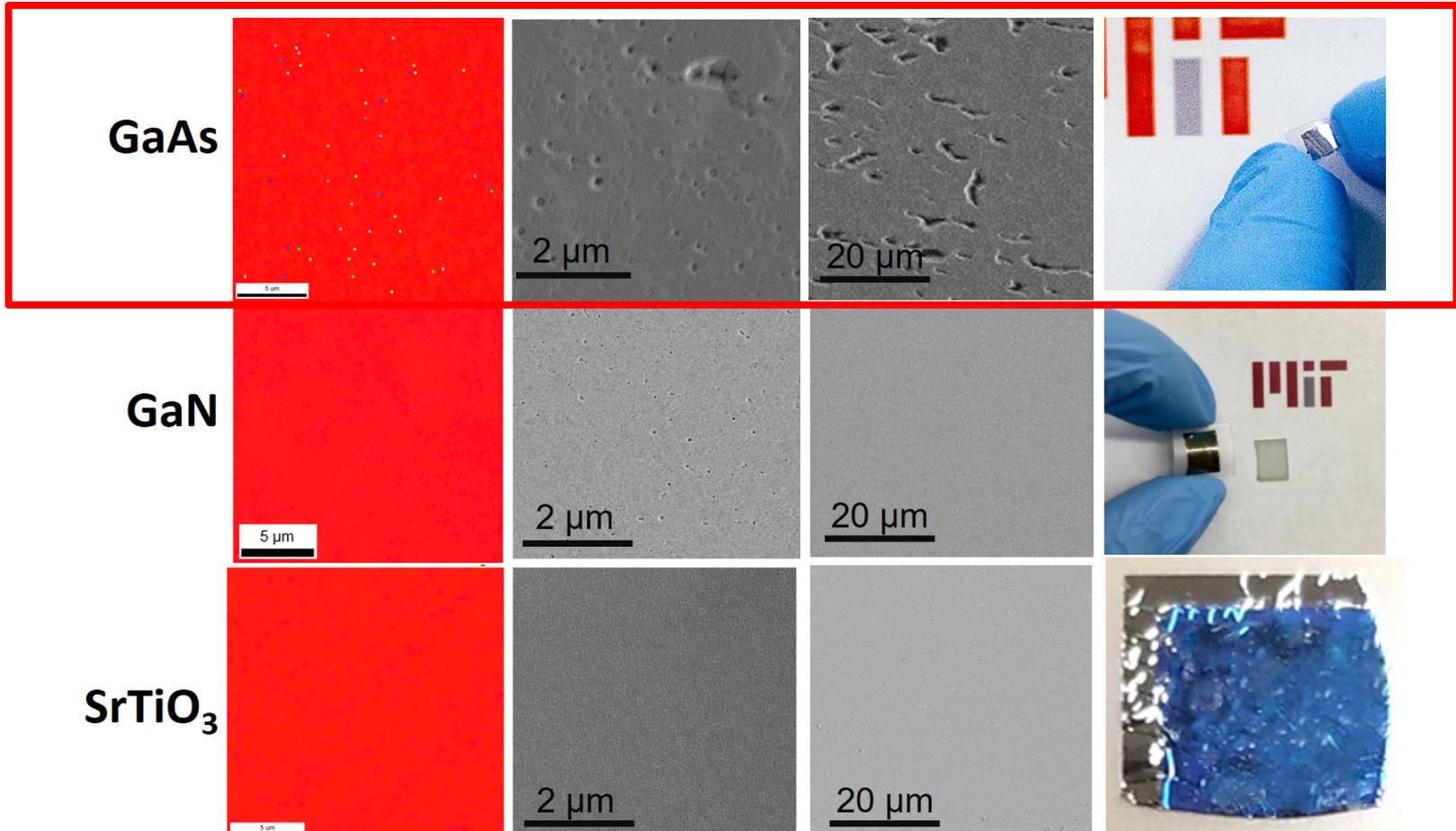
10x10 Micro-LED Array



GaN LED



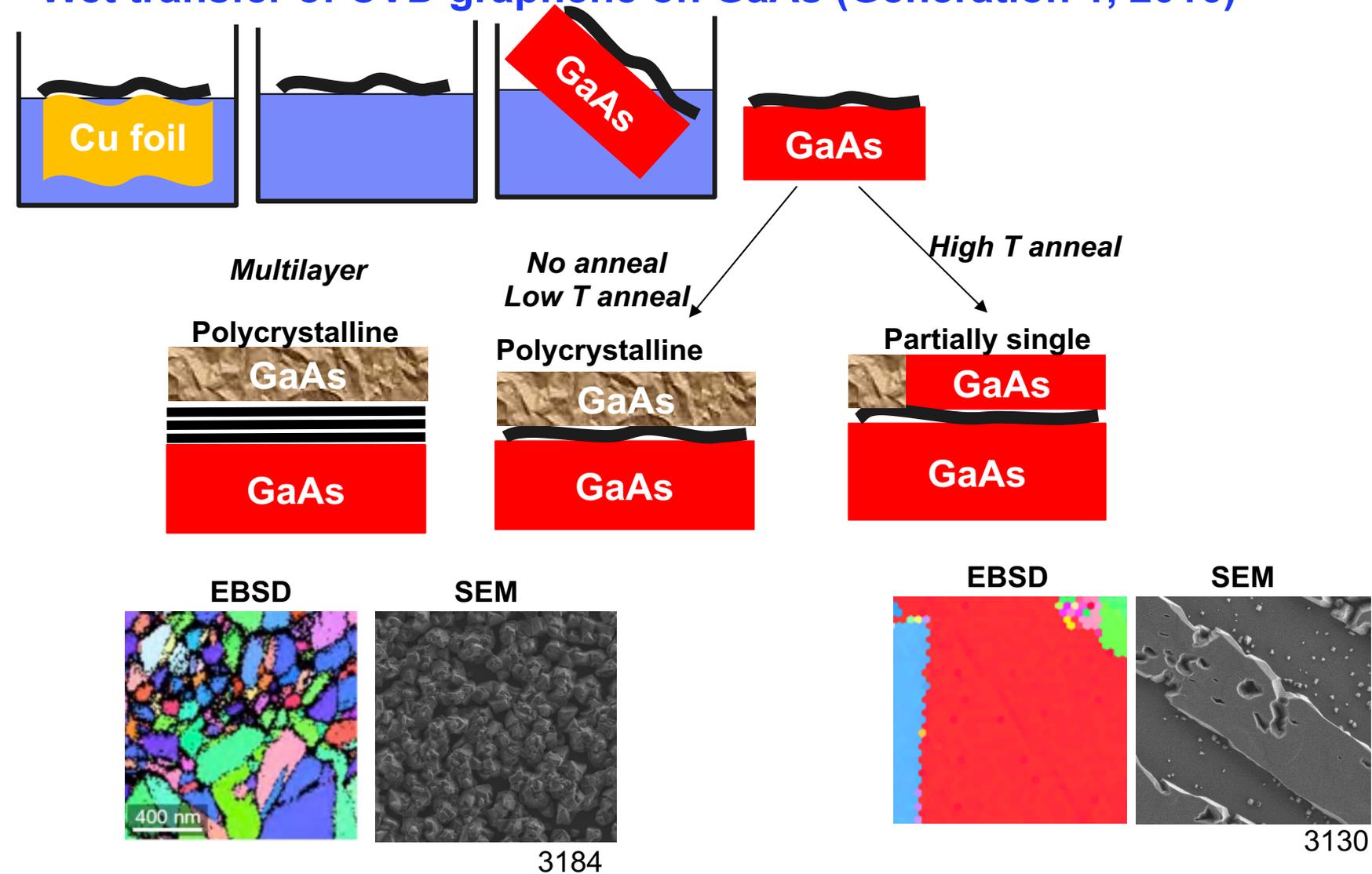
AlInGaP LED



- 1. Weak field penetration due to 30% ionicity**
- 2. Native oxide formation during graphene transfer**

Key to succeed on remote epitaxy: Graphene transfer

Wet transfer of CVD graphene on GaAs (Generation 1, 2016)

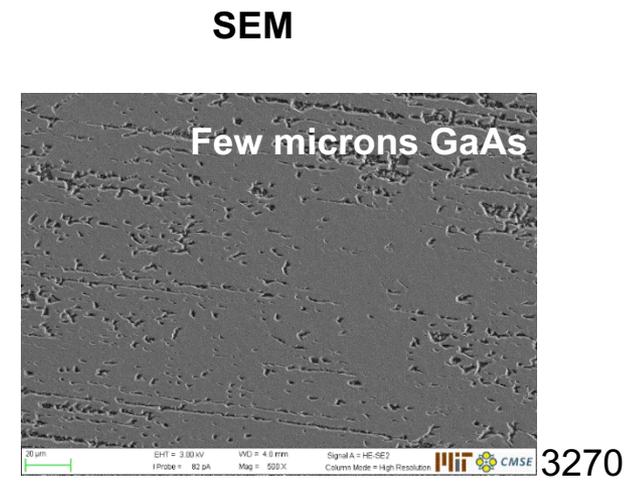
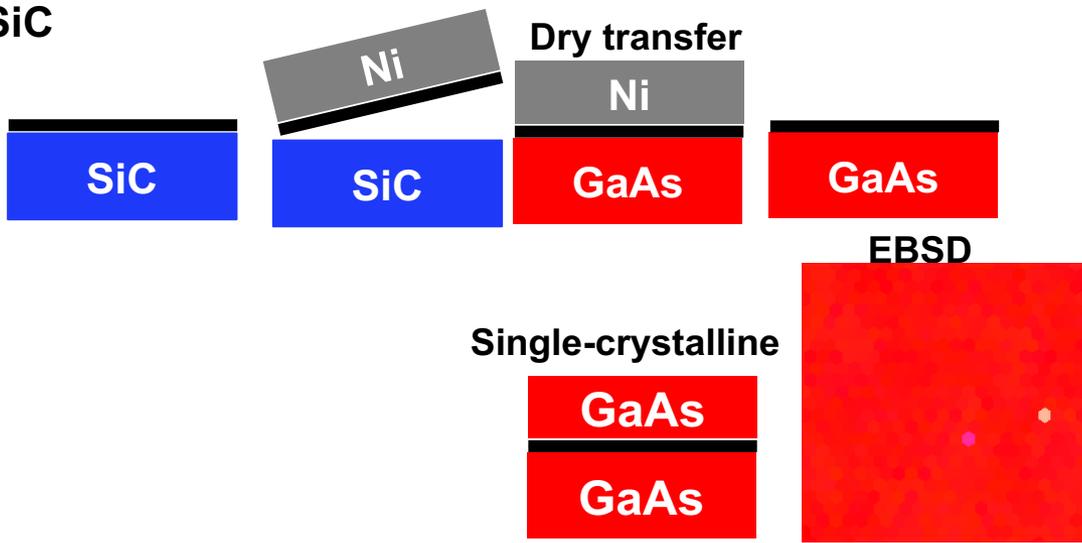


Crystallinity of GaAs completely depends on graphene transfer methods
CVD graphene wet transfer does not allow complete single-crystallinity

Key to succeed on remote epitaxy: Graphene transfer

Dry transfer (LRGT) of epitaxial graphene on GaAs (Generation 2, 2017 Nature)

Forming "epitaxial graphene" on SiC

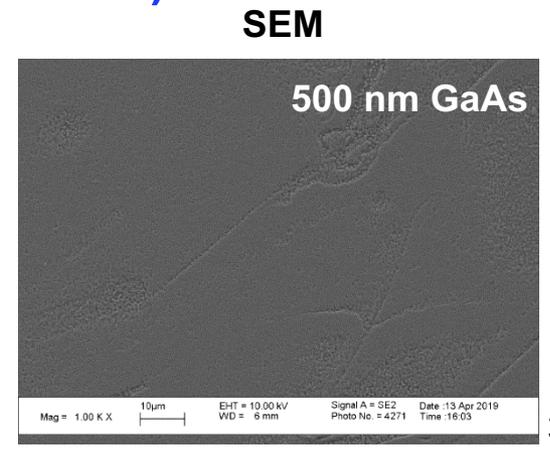
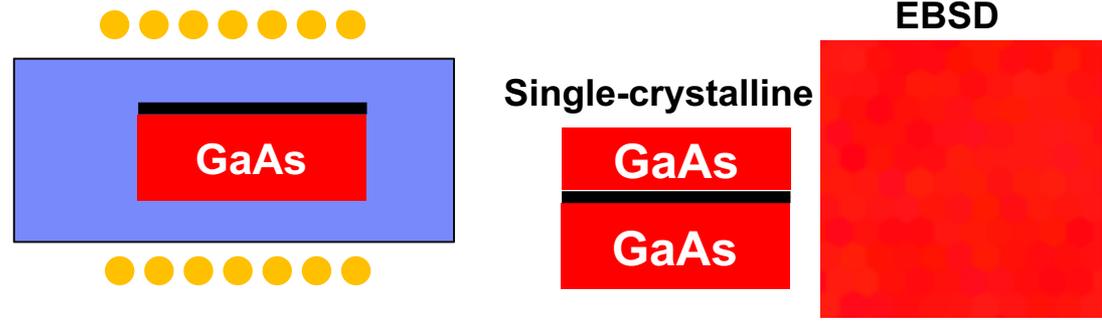


3270

Single-crystallinity secured if epitaxial graphene is dry transferred

Growth of graphene on GaAs (Generation 3, since 2018)

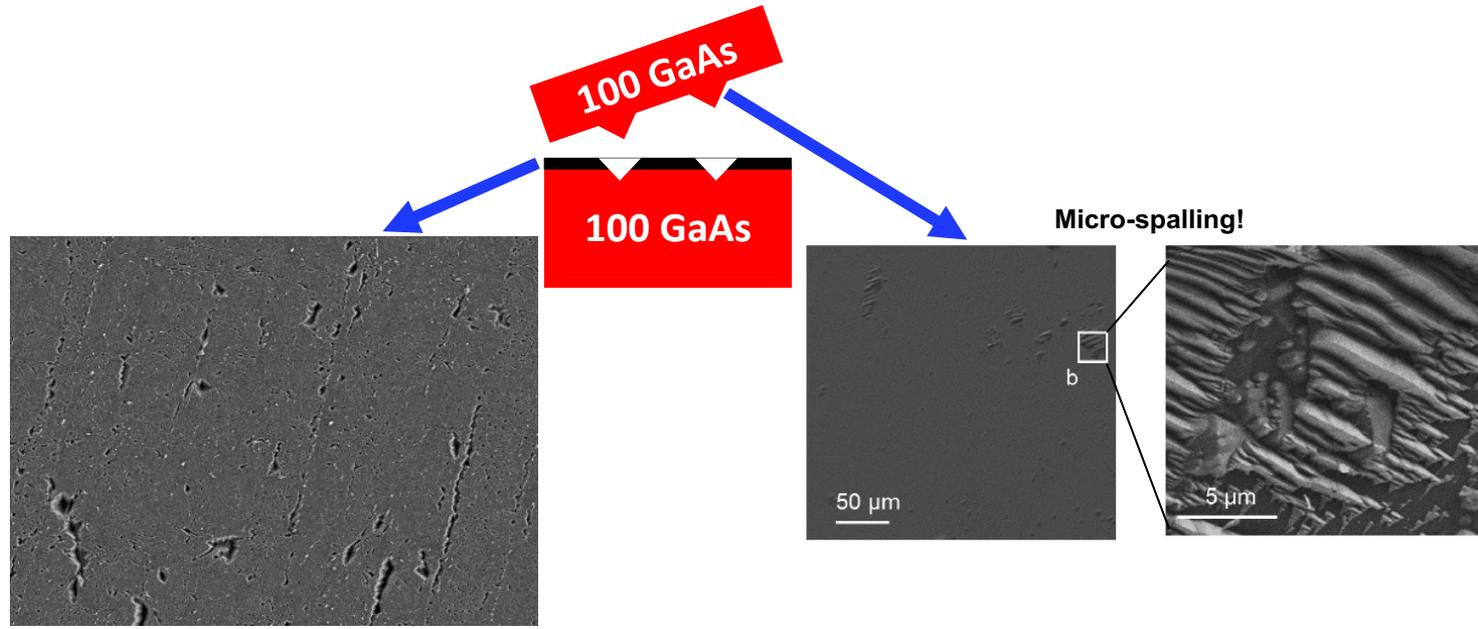
Direct growth in furnace



3732

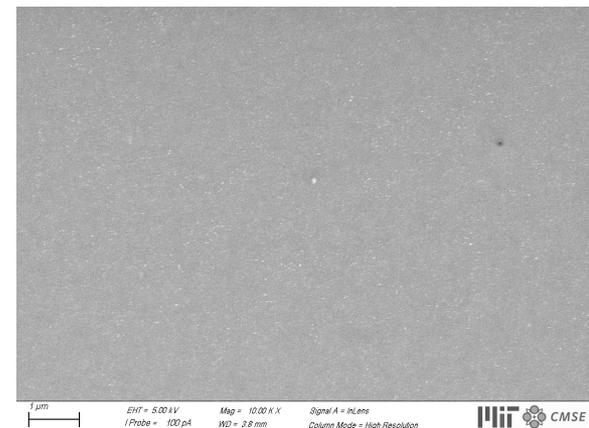
Grown graphene improves morphology

Wafer reusability: Manual graphene transfer creates holes in graphene



- Defect (holes) formation after graphene transfer
- Micro-spalling marks on GaAs form after 2DLT
- Challenging to perform 2nd graphene transfer on GaAs wafers

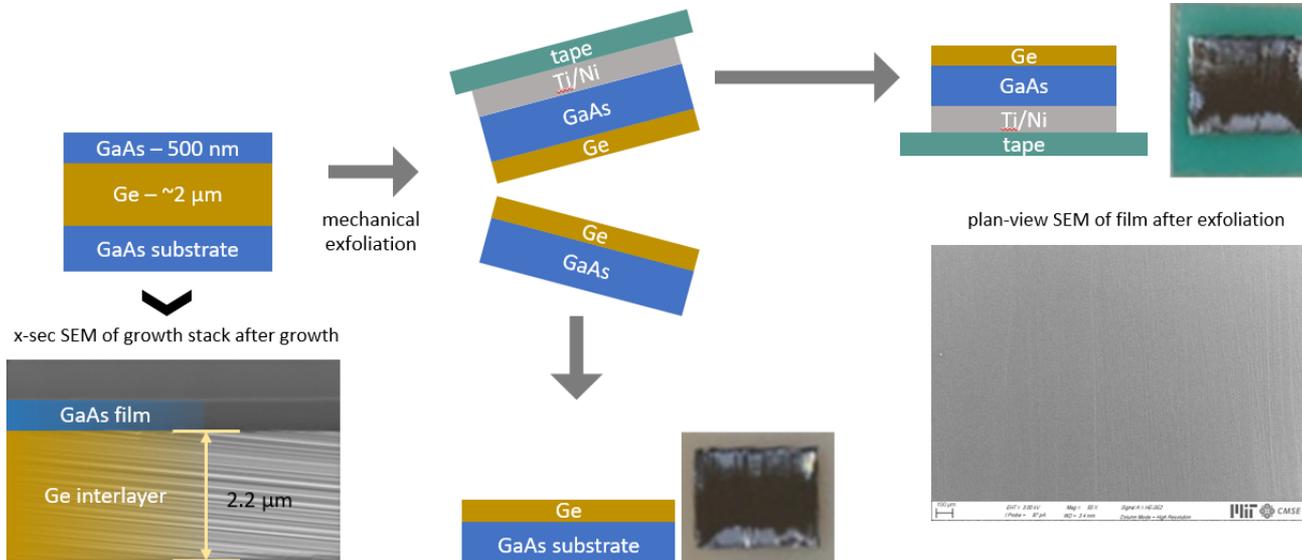
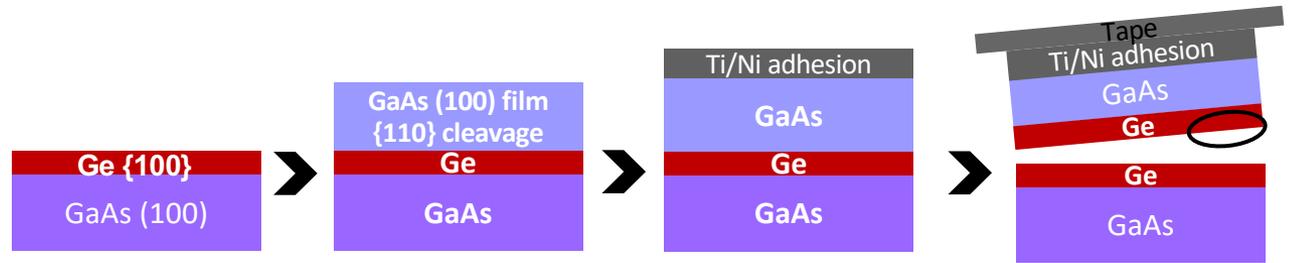
Direct growth of graphene eliminates holes



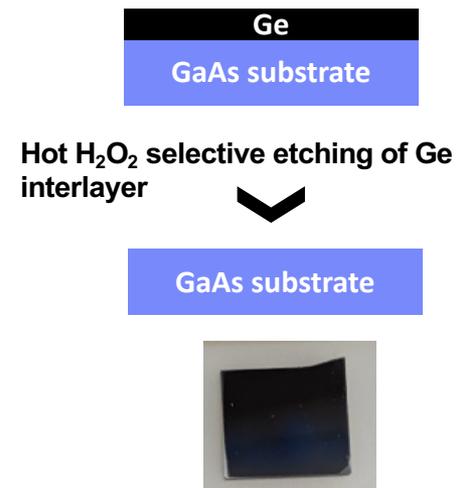
Plan B: Graphene-free mechanical transfer

Cleavage plane assisted exfoliation

materials	Cleavage Plane
Si	{111}
Ge	{100}
GaAs	{110}
GaSb	{100}
InP	{100}
InAs	{100}



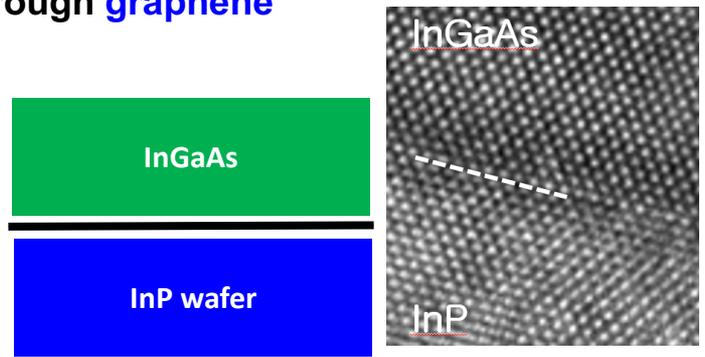
Substrate re-usability



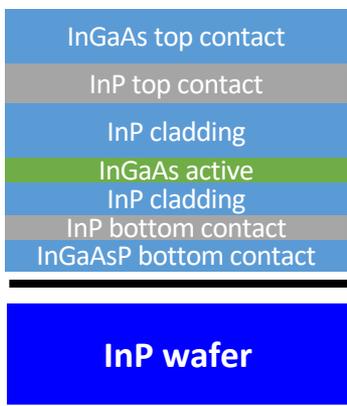


III-V optoelectronics on Si

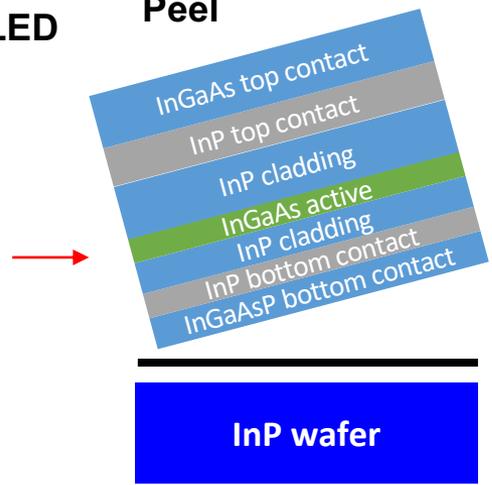
Remote epitaxy of InGaAs through **graphene**



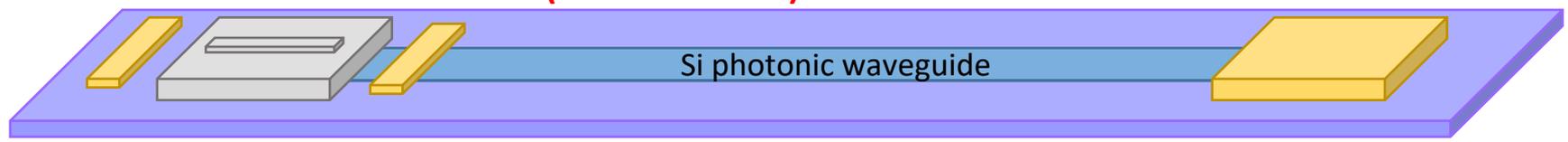
Remote epi of InGaAs LED



Peel



Antenna enhanced LED (TRANSFERRED)

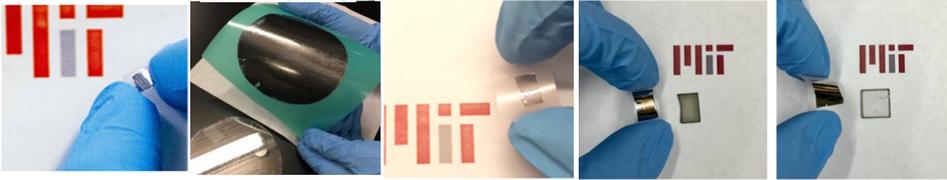


With Prof. Ming Wu

Nanoelectronics Group at MIT

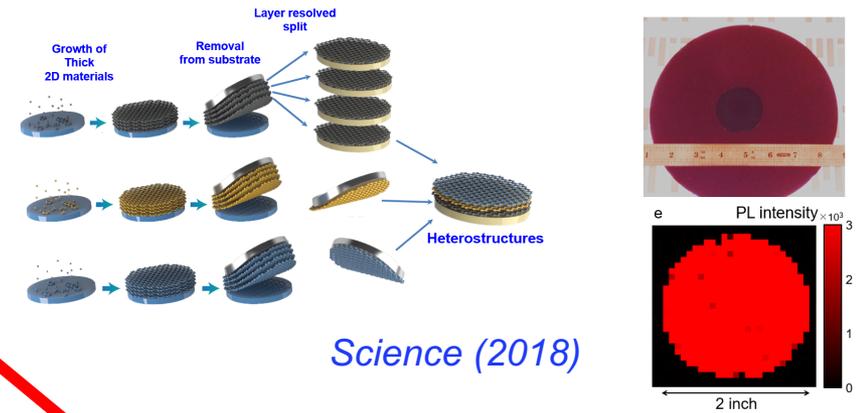
Freestanding semiconductors

GaAs (III-V) GaN (III-N) InP (III-V) SrTiO₃ (Oxide) LiF (fluoride)

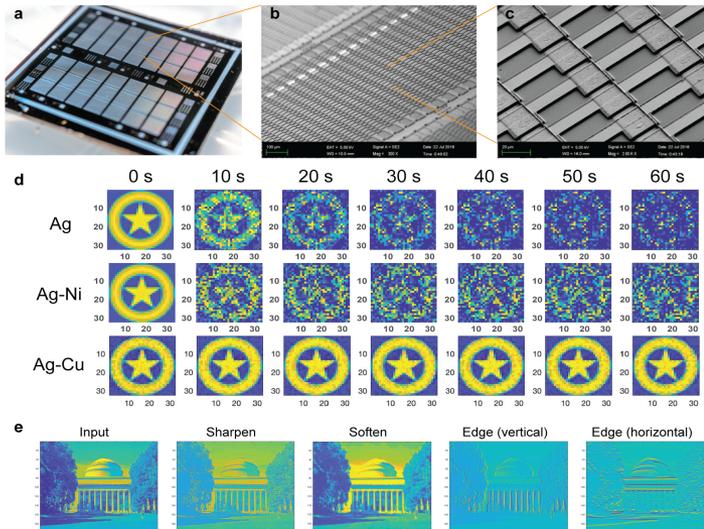


Nature (2017), *Nature Materials* (2018), *Nature Materials* (2019)
Nature Nanotech (2019)

Wafer-scale 2D Materials Group

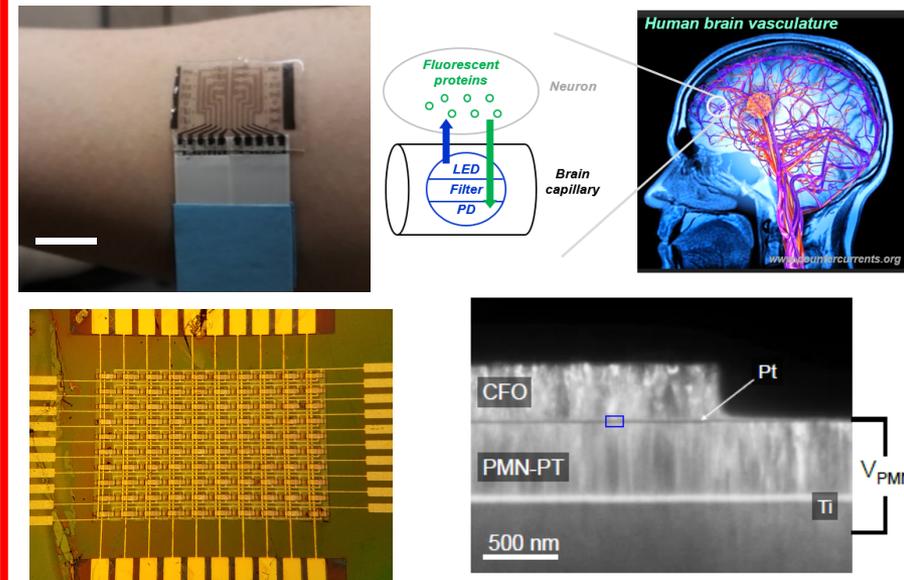


AI hardware



Nature Materials (2018)

Heterointegrations



Nature (2019)